

Specification for Approval

DEVICE NUMBER: BL-XE1361-L

SAMPLES ATTACHED AREA

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2021/3/19	1.0	1.0	1.0	1.0	1.0	1.0	1.0			AND	Original Released
2022.07.07	1.1	1.1	1.1	1.1	1.1	1.1	1.1		0		Standardization
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FOR CUSTOMER'S APPROVAL STAMP OR SIGNATURE

APPROVED	PURCHASE	MANUFACTURE	QUALITY	ENGINEERING
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佰鴻工業股份有限公司 BRIGHT LED ELECTRONICS CORP. 新北市板橋區和平路 19 號 3 樓 3F., No.19, He Ping Road, Ban Qiao Dist., New Taipei City, Taiwan

Tel: +886-2-29591090

Approved By	Confirmed By	Prepared By
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BL-XE1361-L

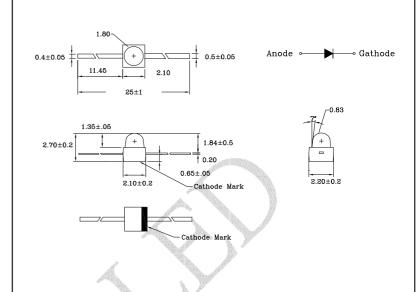
Features:

- 1. Emitted Color: Red.
- 2. Lend Appearance: Water Clear.
- 3. Wide range of collector current.
- 4. Low cost plastic package
- 5. This product doesn't contain restriction Substance, comply ROHS standard.

Applications:

- 1. Indicators
- 2. Automatic Control System

● Package Dimensions:



NOTES:

- 1. All dimensions are in millimeters .
- 2. Tolerance is ±0.10mm unless otherwise specified.
- 3. Specifications are subject to change without notice.

■ Absolute Maximum Ratings(Ta=25°C)

Parameter //	Symbol	Rating	Unit
Power Dissipation	Pd	50	mW
Forward Current	I _F	20	mA
Peak Forward Current *1	I _{FP}	100	mA
Reverse Voltage	V _R	5	V
Operating Temperature	Topr	-40℃~100℃	-
Storage Temperature	Tstg	-40℃~100℃	-
Soldering Temperature	Tsol	See Page 4	-

 $[\]ensuremath{ \bigstar 1}$ Condition for I_FP is pulse of 1/10 duty and 0.1msec width.

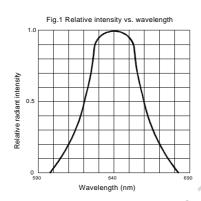


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■ Electrical and optical characteristics(Ta=25°C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	Vf	I _F =2mA	-	1.8	2.4	V
Luminous Intensity	lv	I _F =2mA	1.6	3.0	-	mcd
Reverse Current	I_R	V _R =5V	-	-	100	μΑ
Peak Wave Length	λр	I _F =2mA	-	640	-	nm
Dominant Wave Length	λd	I _F =2mA	626		636	nm
Viewing Angle	2θ _{1/2}	I _F =2mA	-	35	-	deg

■ Typical Electro-Optical Characteristics Curves



vs. ambient temperature

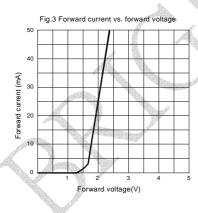
vs. ambient temperature

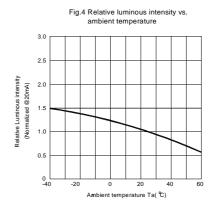
vs. ambient temperature

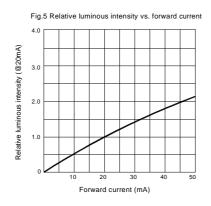
vs. ambient temperature

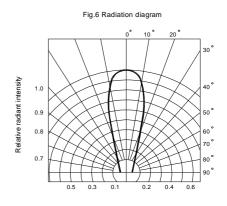
Ambient temperature Ta(%)

Fig.2 Forward current derating curve







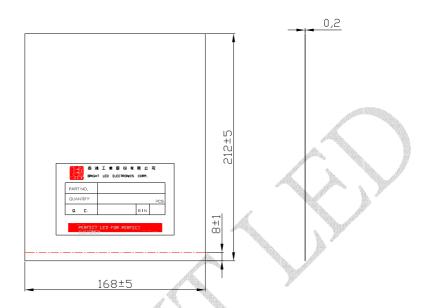




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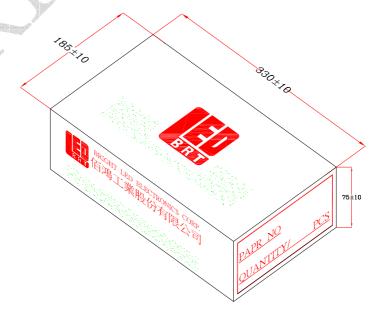
PACKAGING DIMENSIONS

PACKAGING BAG DIMENSIONS(Electrostatic bag)
 Quantity:2000PCS

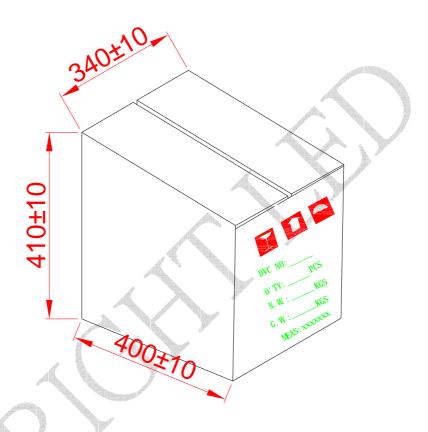


2. PACKAGING BOX DIMENSIONS:

Quantity:10bags/box



3. PACKAGING CARTON DIMENSIONS



NOTES:

- 1.2000PCS PER BAG, 20K PCS PER BOX, 200KPCS PER CARTON
- 2.ALL Dimensions are in millimeters.
- 3. Specifications are subject to change without notice.



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Reliability Test

Classification	Test Item	Reference Standard	Test Conditions	Result
	Operation Life	MIL-STD-750D:1026 MIL-STD-883D:1005 JIS-C-7021 :B-1	Ta: Under room temperature Test time:1,000hrs IF=Product Recommended IF	0/32
Endurance	High Temperature High Humidity Storage	MIL-STD-202F:103B JIS-C-7021 :B-11	Ta:85±5°C RH:90%-95% Test time:240hrs	0/32
Test	High Temperature Storage	MIL-STD-883:1008 JIS-C-7021 :B-10	Ta:100±5℃ Test time:1,000hrs	0/32
	Low Temperature Storage	JIS-C-7021 :B-11	Ta: -45±5°C Test time=1,000hrs	0/32
	Temperature Cycling	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1010 JIS-C-7021 :A-2	Ta:-35±5°C ~25±5°C ~85±5°C ~25±5°C 30min 5min 30min 5min Time: 5cycles	0/32
Environmental	Thermal Shock	MIL-STD-202F:107D(1980) MIL-STD-750D:1051(1995) MIL-STD-883D:1011(1991)	Ta:-45±5°C ~+85±5°C 20min 20 min Time: 10cycles	0/32
Test	Wetting balance	MIL-STD-883:2003 MIL-STD-202F:208D MIL-STD-883D:2003	Ta:230±5℃ Time:5±0.5s	0/32
	Solder Resistance	MIL-STD-202F:210A MIL-STD-883D:1011 JIS-C-7021 :A-1	Ta:260±10°ℂ Time:10±1s	0/32

Judgment criteria of failure for the reliability

	-452°		
Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Forward voltage	V _F (V)	I _F =2mA	Initial Level*1.1
Reverse current	I _R (uA)	V _R =5V	Over U*2
Luminous intensity	Iv (mcd)	I _F =2mA	Initial Level*0.7

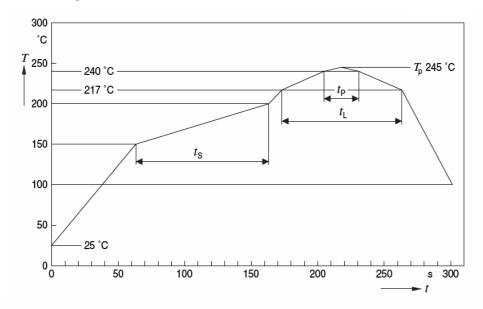
Note: 1.U means the upper limit of specified characteristics.

2. Measurement shall be taken between 2 hours and after the test pieces have been returned to normal ambient conditions after completion of each test.



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IR-Reflow Soldering



Profile Feature	Symbol		Pb-Free (SnAgCu) Assembly			
		Minimum	Recommendation	Maximum		
Ramp-up rate to preheat ^{*)} 25 °C to 150 °C			2	3	K/s	
Time t_S T_{Smin} to T_{Smax}	t _s	60	100	120	s	
Ramp-up rate to peak ^{*)} T _{Smax} to T _P			2	3	K/s	
Liquidus temperature	T_L		217		°C	
Time above liquidus temperature	t _L		80	100	s	
Peak temperature	T _P		245	260	°C	
Time within 5 °C of the specified peak temperature T _p - 5 K	t _P	10	20	30	s	
Ramp-down rate* T _P to 100 °C			3	6	K/s	
Time 25 °C to T _P				480	S	

All temperatures refer to the center of the package, measured on the top of the component

- 1. Avoid any external stress applied to the resin while the LEDs are at high temperature, especially during soldering.
- 2. Avoid rapid cooling or any excess vibration during temperature ramp-down process.
- Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs.

IRON Soldering

350°C Within 3 sec.,One time only.

^{*} slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range



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Notes for designing:

Care must be taken to provide the current limiting resistor in the circuit so as to drive the BRIGHT LEDs within the rated figures. Also, caution should be taken not to overload BRIGHT LEDs with instantaneous voltage at the turning ON and OFF of the circuit.

When using the pulse drive care must be taken to keep the average current within the rated figures. Also, the circuit should be designed so as be subjected to reverse voltage when turning off the BRIGHT LEDs.

Storage:

In order to avoid the absorption of moisture, it is recommended to solder BRIGHT LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

- (1) Temperature : 5° C - 30° C (41°F)Humidity : RH 60% Max.
- (2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:
- a. Completed within 168 hours.
- b. Stored at less than 30% RH.
- (3) Devices require baking before mounting, if: (2) a or (2) b is not met.
- (4) If baking is required, devices must be baked under below conditions: 48 hours at $60^{\circ}\text{C}\pm3^{\circ}\text{C}$.

Package and Label of Products:

- (1) Package: Products are packed in one bag of 2000 pcs (one taping reel) and a label is attached on each bag.
- (2) Label:

